

AMENDMENTS TO THE CLAIMS

Please replace all prior versions, and listings, of claims in the application with the following list of claims:

1. (Currently amended) An integrated circuit comprising one or several metallization levels, metal conductive strips and metal contact pads being formed on a last metallization level, the last level being covered with a passivation layer in which are formed openings above the contact pads, wherein [[a]] an entire thickness of the metal contact pads, at least at a level of their portions not covered by the passivation layer, is smaller than the thickness of said conductive strips.
2. (Original) The integrated circuit of claim 1, wherein at least one conductive strip forms a coil.
3. (Original) The integrated circuit of claim 1, wherein several of said conductive strips form a supply network.
4. (Original) The integrated circuit of claim 1, wherein the last metallization level is formed on an insulating layer, each contact pad being formed of a conductive layer covering an insulating portion laid on the insulating layer.
5. (Original) The integrated circuit of claim 1, wherein the contact pads are made of aluminum.
6. (Original) A method for forming the last metallization level of the integrated circuit of claim 1, comprising:
 - depositing a metal layer on a substrate;
 - etching the metal layer to form metal portions and said conductive strips;
 - covering the substrate, the conductive strips, and the metal portions with a passivation layer;

forming openings in the passivation layer above the metal portions; and
partially etching the metal portions to decrease their thickness to obtain said contact pads.

7. (Original) A method for forming the last metallization level of the integrated circuit of claim 1, comprising:

depositing a metal layer on a substrate;
etching the metal layer to form metal portions and said conductive strips;
covering the conductive strips with a protection layer;
partially etching the metal portions to decrease their thickness to obtain said contact pads;
removing, if necessary, the protection layer;
covering the substrate, the conductive strips, and the contact pads with a passivation layer;

and

forming openings in the passivation layer above the contact pads.